

SED10070GG

N-Channel Enhancement-Mode MOSFET

Revision: A

General Description

Advanced trench technology to provide excellent RDS(ON), low gate charge and low operation voltage. This device is suitable for using as a load switch or in PWM applications.

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device

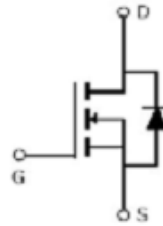
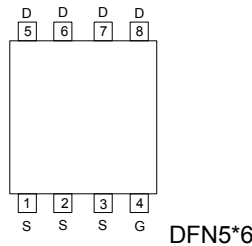
Features

For a single MOSFET

- $V_{DS} = 100V$
- $R_{DS(ON)} = 8.2m\Omega @ V_{GS}=10V$

Pin configurations

See Diagram below



Absolute Maximum Ratings

| Parameter | | Symbol | Rating | Units |
|--|-----------------------------|----------|------------|-------|
| Drain-Source Voltage | | V_{DS} | 100 | V |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| Drain Current | Continuous ^{1,2,3} | I_D | 70 | A |
| | Pulsed | | 280 | |
| Total Power Dissipation | @TA=25°C | P_D | 170 | W |
| Single-pulse avalanche energy ⁴ | | E_{AS} | 580 | mJ |
| Operating Junction Temperature Range | | T_J | -55 to 150 | °C |

Thermal Resistance

| Symbol | Parameter | Min | Typ | Units |
|-----------------|---------------------|-----|------|-------|
| $R_{\theta JA}$ | Junction to Ambient | | 0.88 | °C/W |

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| Electrical Characteristics (T _J =25°C unless otherwise noted) | | | | | | |
|--|--------------------------------------|--|-----|------|-----|-------|
| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
| OFF CHARACTERISTICS (Note 2) | | | | | | |
| B _V DSS | Drain-Source Breakdown Voltage | I _D =250μA, V _{GS} =0 V | 100 | | | V |
| I _{DSS} | Drain to Source Leakage Current | V _{DS} = 100V, V _{GS} =0V | | | 1 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =20 V | | | 100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D =250μA | 2 | 3 | 4 | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V, I _D =39A | | 8.2 | 9.8 | mΩ |
| g _{FS} | Forward Transconductance | V _{DS} = 25V, I _D =28A | 32 | | | S |
| DYNAMIC PARAMETERS | | | | | | |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =25V, f=1MHz | | 4400 | | pF |
| C _{oss} | Output Capacitance | | | 320 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 240 | | pF |
| SWITCHING PARAMETERS | | | | | | |
| Q _g | Total Gate Charge ² | V _{DD} =80V, V _{GS} =10V, I _D =39A | | 95 | | nC |
| Q _{gs} | Gate Source Charge | | | 18 | | nC |
| Q _{gd} | Gate Drain Charge | | | 25 | | nC |
| t _{d(on)} | Turn-On Delay Time | V _{DD} =50V, V _{GS} =10V, I _D =39A, R _{GEN} =2.5Ω | | 12 | | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 45 | | ns |
| t _{d(r)} | Turn-On Rise Time | | | 55 | | ns |
| t _{d(f)} | Turn-Off Fall Time | | | 47 | | ns |
| Source-Drain Characteristics | | | | | | |
| Symbol | Parameter | Test Condition | Min | Typ | Max | Units |
| V _{SD} | Diode forward voltage | V _{GS} =0V, I _S =100A | | 0.85 | 1.2 | V |
| I _S | Diode forward current | | | | 57 | A |
| T _{rr} | Reverse recovery time ⁷ | T _J =25°C, I _F =28A di/dt=100A/μs | | 36 | | ns |
| Q _{rr} | Reverse recovery charge ⁷ | | | | 56 | |

Typical Characteristics

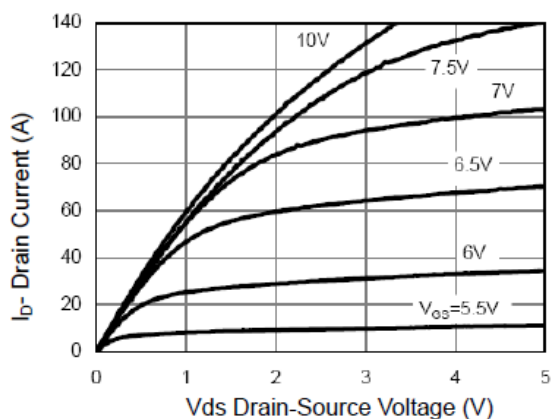


Figure 1 Output Characteristics

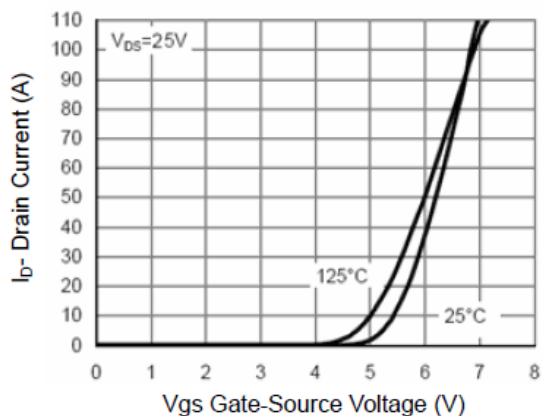


Figure 2 Transfer Characteristics

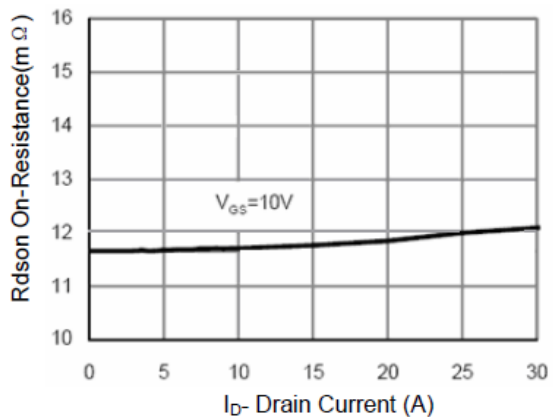


Figure 3 $R_{DS(on)}$ - Drain Current

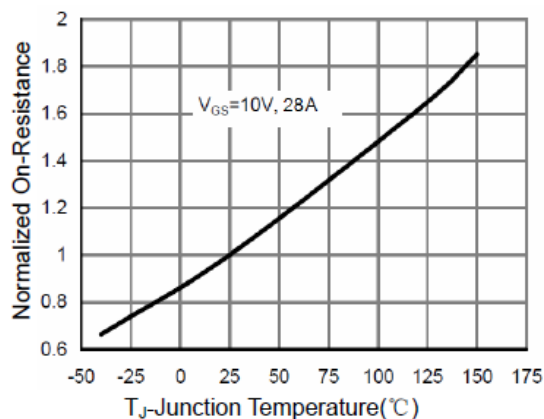


Figure 4 $R_{DS(on)}$ -Junction Temperature

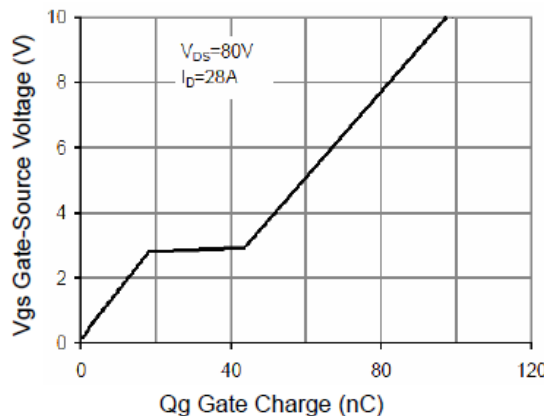


Figure 5 Gate Charge

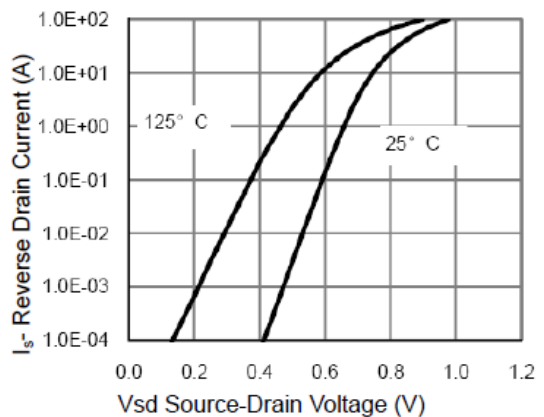


Figure 6 Source- Drain Diode Forward

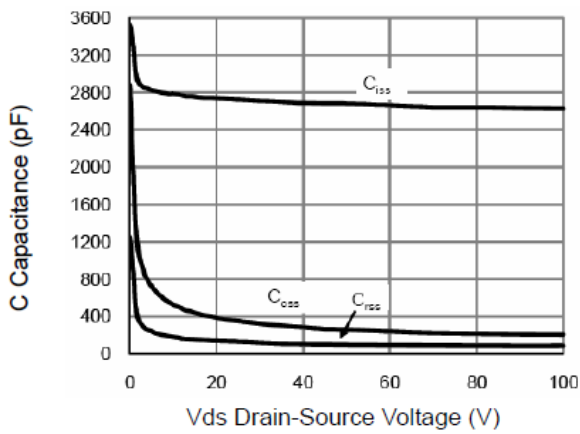


Figure 7 Capacitance vs Vds

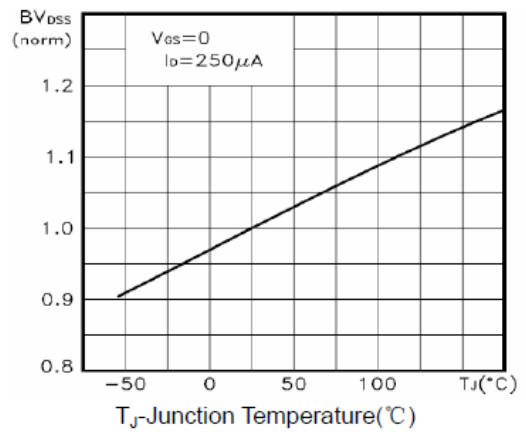


Figure 9 BV_{DSS} vs Junction Temperature

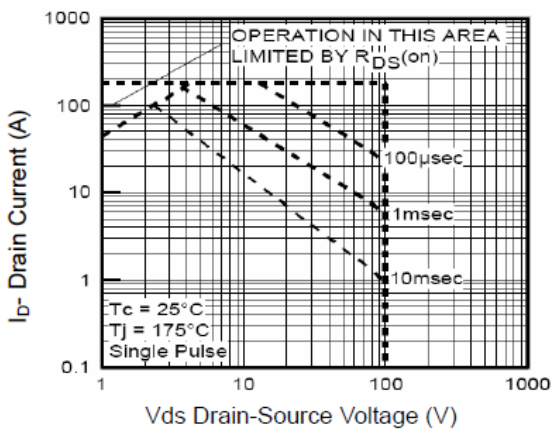


Figure 8 Safe Operation Area

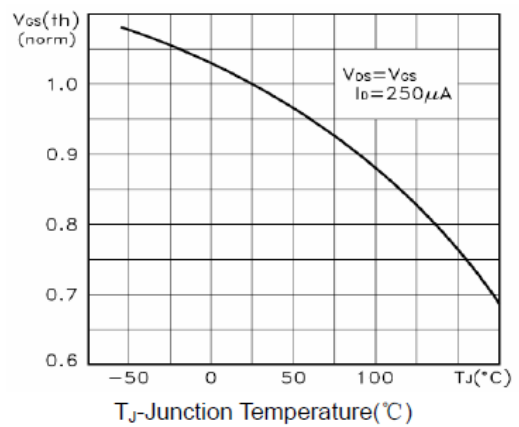


Figure 10 $V_{GS(th)}$ vs Junction Temperature

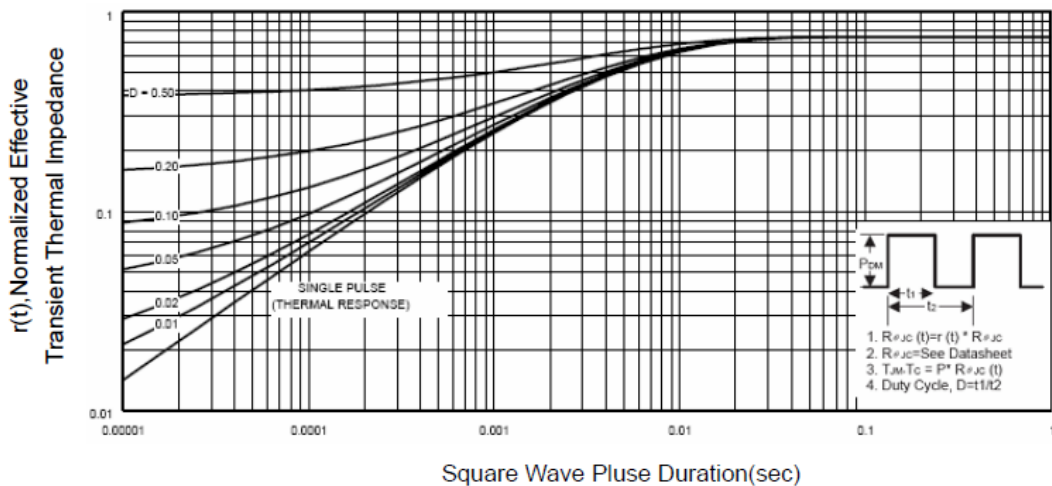
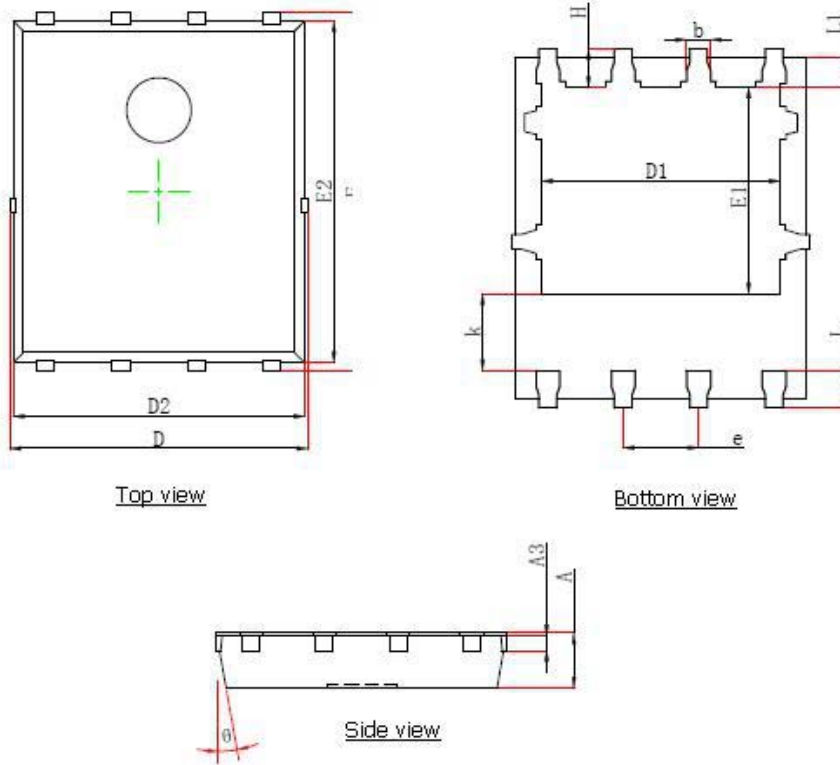


Figure 11 Normalized Maximum Transient Thermal Impedance

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Package Outline Dimension

DFN5 × 6



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.900 | 1.000 | 0.035 | 0.039 |
| A3 | 0.254REF. | | 0.010REF. | |
| D | 4.944 | 5.096 | 0.195 | 0.201 |
| E | 5.974 | 6.126 | 0.235 | 0.241 |
| D1 | 3.910 | 4.110 | 0.154 | 0.162 |
| E1 | 3.375 | 3.575 | 0.133 | 0.141 |
| D2 | 4.824 | 4.976 | 0.190 | 0.196 |
| E2 | 5.674 | 5.826 | 0.223 | 0.229 |
| k | 1.190 | 1.390 | 0.047 | 0.055 |
| b | 0.350 | 0.450 | 0.014 | 0.018 |
| e | 1.270TYP. | | 0.050TYP. | |
| L | 0.559 | 0.711 | 0.022 | 0.028 |
| L1 | 0.424 | 0.576 | 0.017 | 0.023 |
| H | 0.574 | 0.726 | 0.023 | 0.029 |
| θ | 10° | 12° | 10° | 12° |

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